

AN 108:25924 HCA
TI Silver alloy for brazes
IN Kashiwagi, Kozo
PA Tanaka Noble Metal Industrial Co., Ltd., Japan
SO Jpn. Tokkyo Koho, 3 pp.

CODEN: JAXXAD

DT Patent
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----	----	-----	-----	-----
PI	JP 62036798	B4	19870808	JP 1979-81796	19790628 <--
AB	The brazes contg. 63-90% Ag, 0.05-4.5% Ni, Sn, and/or In, and balance Cu are used in vacuum tubes, electronic tubes, or large-scale integrated circuits to develop smooth joints for low corrosion and discoloring. Thus, a Cu specimen was brazed with Ag alloy contg. Cu 36, In 0.1, and Sn 0.15%. Surface crack no. was 3, and av. depth of cracks on the brazed surface was 2.mu., vs. 12 and 6.5.mu. when Ag-34% Cu braze was used.				